

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
Yeo et al. )  
Serial No.: )  
Filed : )  
For : **ENHANCED CHIP SCALE PACKAGE** )  
**FOR WIRE BOND DIES** )  
Attorney's Docket No.: 4795-002 )

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Raleigh, North Carolina  
February 19, 2002

Commissioner for Patents  
BOX PATENT APPLICATION  
Washington, D.C. 20231

Dear Sir:

**CLAIM OF PRIORITY**

The applicant in this case claims priority based on a prior application filed in Singapore and identified as Singapore Patent Application No. 200106786-7 filed November 2, 2001.

A certified copy of the Singapore application will be submitted in due course.

Respectfully submitted,

**COATS & BENNETT, P.L.L.C.**

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